

**IN THE UNITED STATES DISTRICT COURT  
FOR THE DISTRICT OF DELAWARE**

ELM 3DS INNOVATIONS, LLC,

Plaintiff,

v.

SAMSUNG ELECTRONICS CO., LTD., et al.,

Defendants.

C.A. No. 14-cv-1430-LPS

JURY TRIAL DEMANDED

ELM 3DS INNOVATIONS, LLC,

Plaintiff,

v.

MICRON TECHNOLOGY, INC., et al.,

Defendants.

C.A. No. 14-cv-1431-LPS

JURY TRIAL DEMANDED

ELM 3DS INNOVATIONS, LLC,

Plaintiff,

v.

SK HYNIX INC., et al.,

Defendants.

C.A. No. 14-cv-1432-LPS

JURY TRIAL DEMANDED

**[PROPOSED] ORDER MODIFYING CLAIM CONSTRUCTION**

Having considered Defendants' Motion for Clarification Under L.R. 7.1.5 and all papers filed in support of and opposition to the Motion, IT IS HEREBY ORDERED that:

The terms “dice is substantially flexible” and “die is substantially flexible” mean a “dice/die that is largely able to bend without breaking and contains a substantially flexible semiconductor substrate, that is thinned to 50  $\mu\text{m}$  or less and subsequently polished or smoothed such that it is largely able to bend without breaking, and a sufficiently low tensile stress dielectric material.”

DATED: \_\_\_\_\_

\_\_\_\_\_  
Chief, United States District Judge